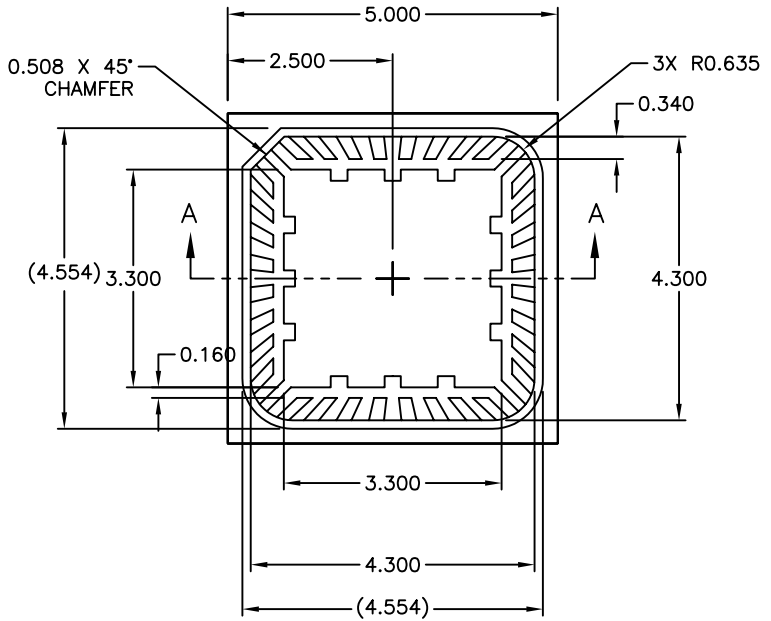
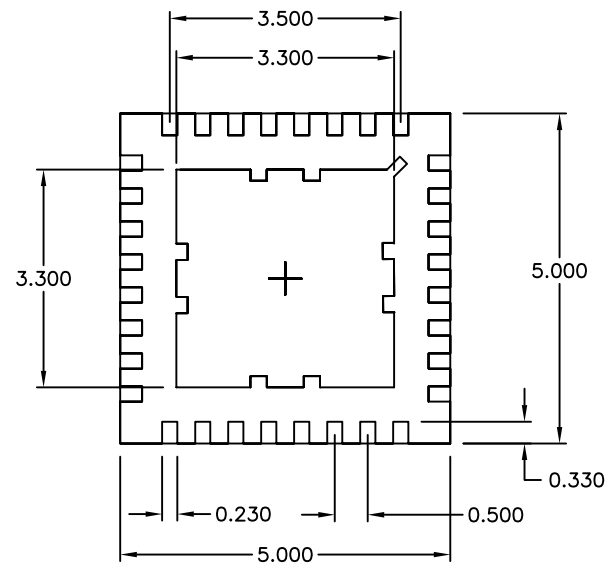
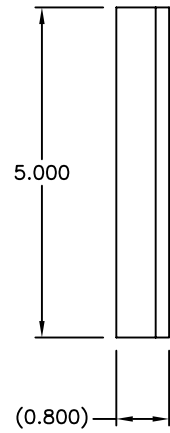


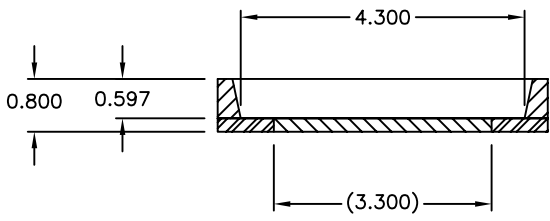
SEMPAK REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
10760	10/12/06	PRODUCTION RELEASE	D.MORRIS



TOP VIEW



BOTTOM VIEW



SECTION A-A

- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
 3. LEAD FRAME: COPPER, 194 FH.
 4. LEAD FINISH: FULL GOLD PLATE.
 5. FRAME THICKNESS: 0.2030 ± 0.0076.
 6. DIE PAD: 3.300mm X 3.300mm.
 7. JEDEC OUTLINE: MO-220 (VHHD-4).

THIRD ANGLE PROJECTION

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE:

X.XX ± 0.015 X.XXXX ± ---
 X.XXX ± 0.050 ANGLES: ± 1°

DO NOT SCALE DRAWING

DRAWN BY	C. CRUZ	DATE	10/12/06
APP BY	P. FLASKERUD	DATE	10/12/06
CUSTOMER	---		
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32 LEAD 5mm X 5mm
 MLP Open-Pak

SIZE	PART NO.	REV
A	MLP5X5-32-OP-01	2
SCALE	NONE	CAD FILE
	MLP5X5-32-OP-01-R2.DWG	SHEET 1 OF 1